

N-Channel 600V (D-S) Super Junction Power MOSFET

PRODUCT SUMMARY		
V _{DS} (V) at T _J max.	600	
R _{DS(on)} at 25 °C (Ω)	V _{GS} = 10 V	0.150

FEATURES

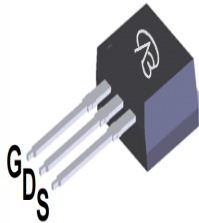
- Low figure-of-merit (FOM) R_{on} x Q_g
- Low input capacitance (C_{iss})
- Reduced switching and conduction losses
- Ultra low gate charge (Q_g)
- Avalanche energy rated (UIS)



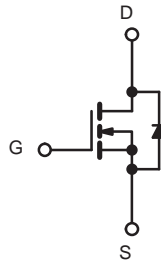
APPLICATIONS

- Server and telecom power supplies
- Switch mode power supplies (SMPS)
- Power factor correction power supplies (PFC)
- Lighting
 - High-intensity discharge (HID)
 - Fluorescent ballast lighting

TO-262



Top View



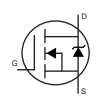
N-Channel MOSFET

ABSOLUTE MAXIMUM RATINGS (T _C = 25 °C, unless otherwise noted)			
PARAMETER	SYMBOL	LIMIT	UNIT
Drain-Source Voltage	V _{DS}	600	V
Gate-Source Voltage	V _{GS}	± 30	
Continuous Drain Current (T _J = 150 °C)	V _{GS} at 10 V	T _C = 25 °C	20
		T _C = 100 °C	12
Pulsed Drain Current ^a	I _{DM}	60	A
Linear Derating Factor		1.67	W/°C
Single Pulse Avalanche Energy ^b	E _{AS}	900	mJ
Maximum Power Dissipation	P _D	160	W
Operating Junction and Storage Temperature Range	T _J , T _{stg}	-55 to +150	°C
Drain-Source Voltage Slope	dV/dt	T _J = 125 °C	50
Reverse Diode dV/dt ^d		15	
Soldering Recommendations (Peak Temperature) ^c	for 10 s	260	°C

Notes

- Repetitive rating; pulse width limited by maximum junction temperature.
- V_{DD} = 100 V, starting T_J = 25 °C, L = 30mH, R_g = 25 Ω, I_{AS} = 13A.
- 1.6 mm from case.
- I_{SD} ≤ I_D, dI/dt = 100 A/μs, starting T_J = 25 °C.

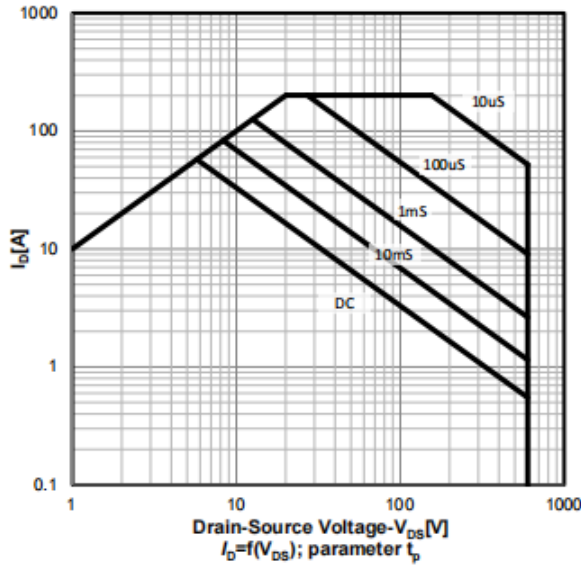
THERMAL RESISTANCE RATINGS				
PARAMETER	SYMBOL	TYP.	MAX.	UNIT
Maximum Junction-to-Ambient	R_{thJA}	-	62	°C/W
Maximum Junction-to-Case (Drain)	R_{thJC}	-	0.38	

SPECIFICATIONS ($T_J = 25\text{ }^\circ\text{C}$, unless otherwise noted)							
PARAMETER	SYMBOL	TEST CONDITIONS		MIN.	TYP.	MAX.	UNIT
Static							
Drain-Source Breakdown Voltage	V_{DS}	$V_{GS} = 0\text{ V}, I_D = 1\text{ mA}$		600	-	-	V
V_{DS} Temperature Coefficient	$\Delta V_{DS}/T_J$	Reference to $25\text{ }^\circ\text{C}$, $I_D = 1\text{ mA}$		-	0.70	-	V/°C
Gate-Source Threshold Voltage (N)	$V_{GS(th)}$	$V_{DS} = V_{GS}, I_D = 250\text{ }\mu\text{A}$		2.5	-	4.5	V
Gate-Source Leakage	I_{GSS}	$V_{GS} = \pm 20\text{ V}$		-	-	± 100	nA
		$V_{GS} = \pm 30\text{ V}$		-	-	± 1	μA
Zero Gate Voltage Drain Current	I_{DSS}	$V_{DS} = 600\text{ V}, V_{GS} = 0\text{ V}$		-	-	1	μA
		$V_{DS} = 480\text{ V}, V_{GS} = 0\text{ V}, T_J = 125\text{ }^\circ\text{C}$		-	-	100	
Drain-Source On-State Resistance	$R_{DS(on)}$	$V_{GS} = 10\text{ V}$	$I_D = 7\text{ A}$	-	0.150	-	Ω
Forward Transconductance	g_{fs}	$V_{DS} = 30\text{ V}, I_D = 7\text{ A}$		-	5.6	-	S
Dynamic							
Input Capacitance	C_{iss}	$V_{GS} = 0\text{ V}, V_{DS} = 100\text{ V}, f = 1\text{ MHz}$		-	2300	-	pF
Output Capacitance	C_{oss}			-	330	-	
Reverse Transfer Capacitance	C_{rss}			-	4	-	
Effective Output Capacitance, Energy Related ^a	$C_{o(er)}$	$V_{DS} = 0\text{ V to } 520\text{ V}, V_{GS} = 0\text{ V}$		-	63	-	
Effective Output Capacitance, Time Related ^b	$C_{o(tr)}$			-	213	-	
Total Gate Charge	Q_g	$V_{GS} = 10\text{ V}$	$I_D = 20\text{ A}, V_{DS} = 520\text{ V}$	-	62	-	nC
Gate-Source Charge	Q_{gs}			-	39	-	
Gate-Drain Charge	Q_{gd}			-	4.7	-	
Turn-On Delay Time	$t_{d(on)}$	$V_{DD} = 520\text{ V}, I_D = 20\text{ A}, V_{GS} = 10\text{ V}, R_g = 9.1\text{ }\Omega$		-	18	25	ns
Rise Time	t_r			-	24	55	
Turn-Off Delay Time	$t_{d(off)}$			-	8.0	-	
Fall Time	t_f			-	1.2	-	
Gate Input Resistance	R_g	$f = 1\text{ MHz}, \text{ open drain}$		-	0.8	-	Ω
Drain-Source Body Diode Characteristics							
Continuous Source-Drain Diode Current	I_S	MOSFET symbol showing the integral reverse p-n junction diode 		-	-	20	A
Pulsed Diode Forward Current	I_{SM}			-	-	60	
Diode Forward Voltage	V_{SD}	$T_J = 25\text{ }^\circ\text{C}, I_S = 8\text{ A}, V_{GS} = 0\text{ V}$		-	-	1.5	V
Reverse Recovery Time	t_{rr}	$T_J = 25\text{ }^\circ\text{C}, I_F = I_S = 8\text{ A}, di/dt = 100\text{ A}/\mu\text{s}, V_R = 400\text{ V}$		-	520	-	ns
Reverse Recovery Charge	Q_{rr}			-	5.8	-	μC
Reverse Recovery Current	I_{RRM}			-	4.5	-	A

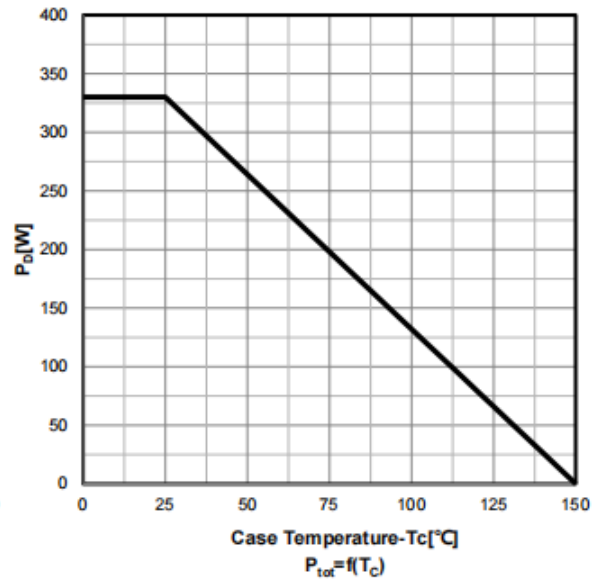
Notes

- a. $C_{oss(er)}$ is a fixed capacitance that gives the same energy as C_{oss} while V_{DS} is rising from 0 % to 80 % V_{DSS} .
- b. $C_{oss(tr)}$ is a fixed capacitance that gives the same charging time as C_{oss} while V_{DS} is rising from 0 % to 80 % V_{DSS} .

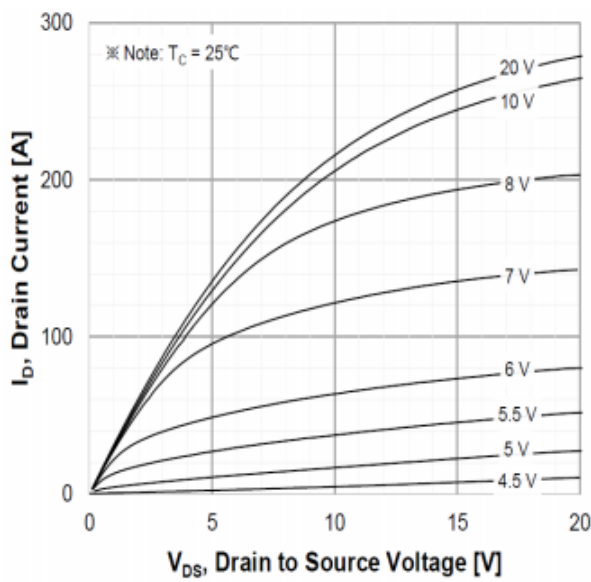
Safe operating area TC=25 °C
TO-247



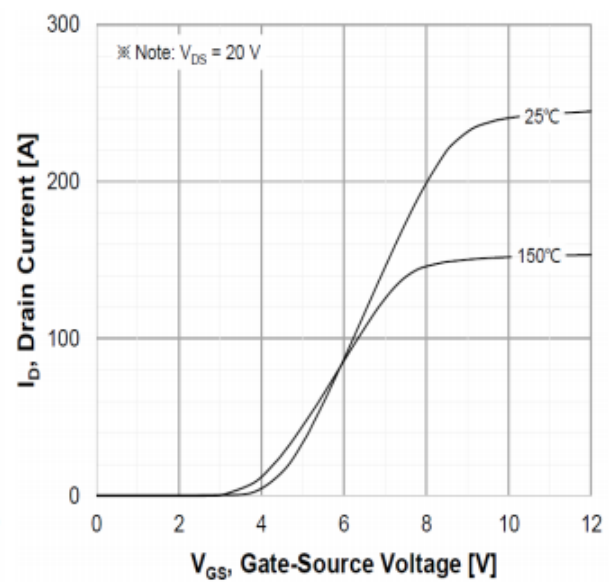
Power dissipation



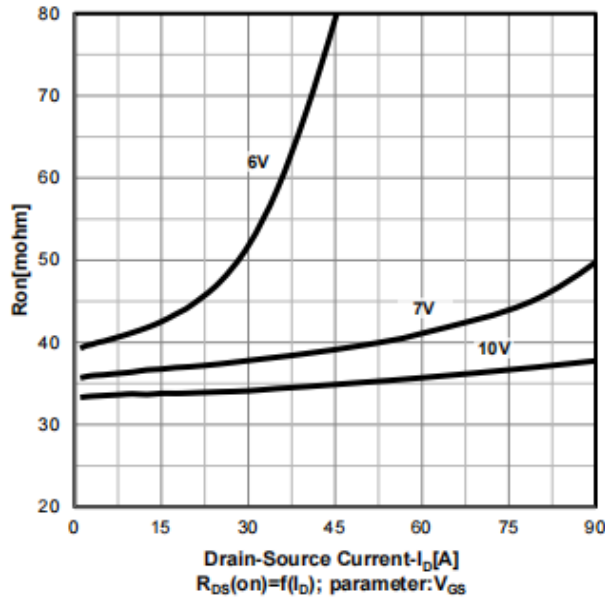
Typ. output characteristics $T_J=25\text{ °C}$



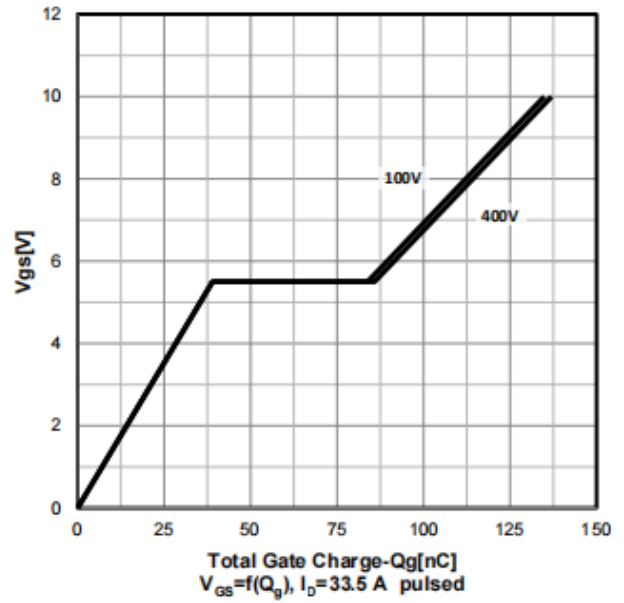
Transfer characteristics



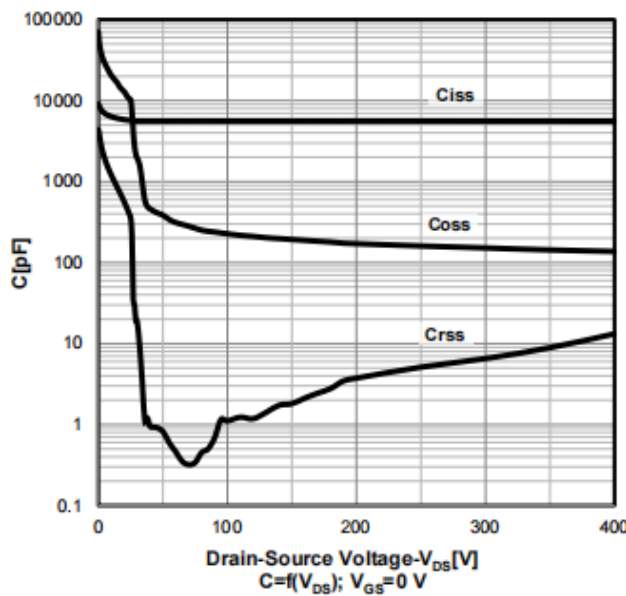
Typ. drain-source on-state resistance



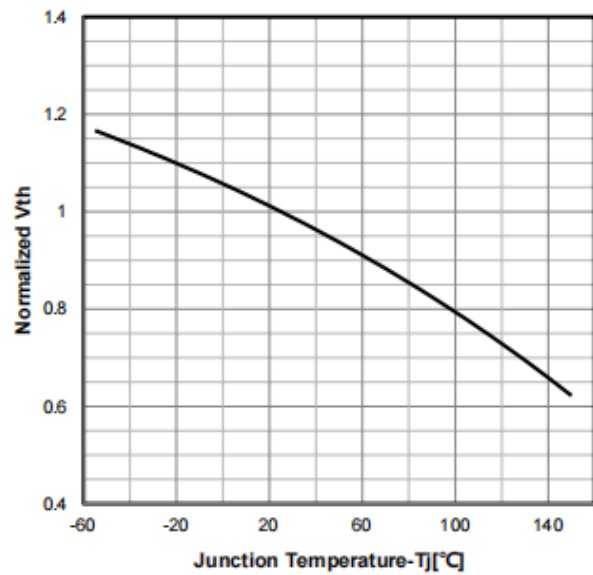
Typ. gate charge characteristics



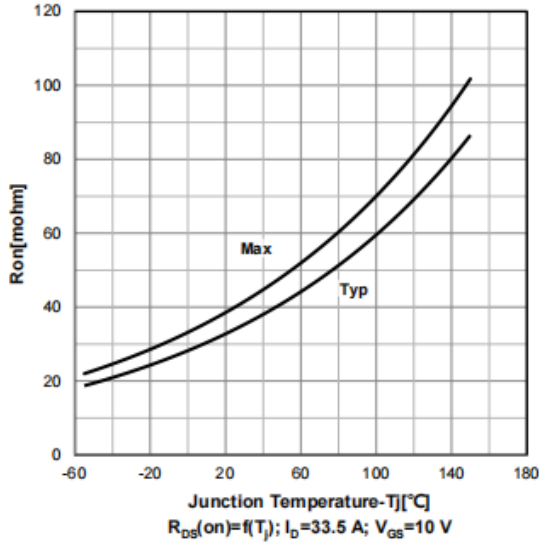
Typ. capacitances



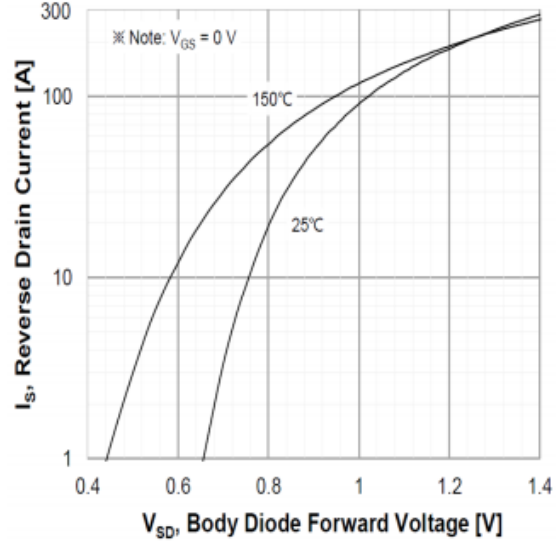
Normalized $V_{GS(th)}$ characteristics



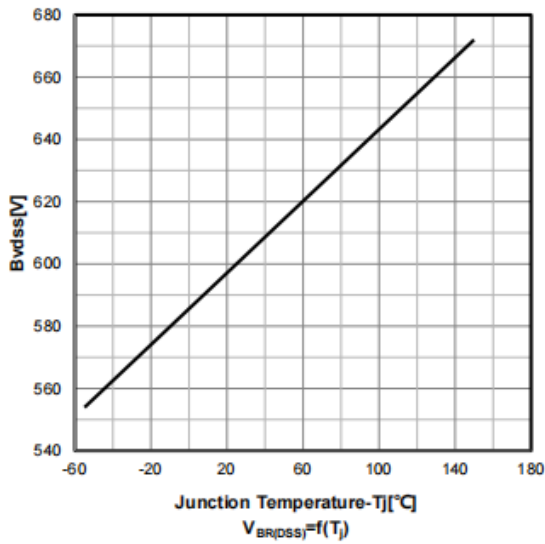
On-resistance vs temperature



Forward characteristics of reverse diode



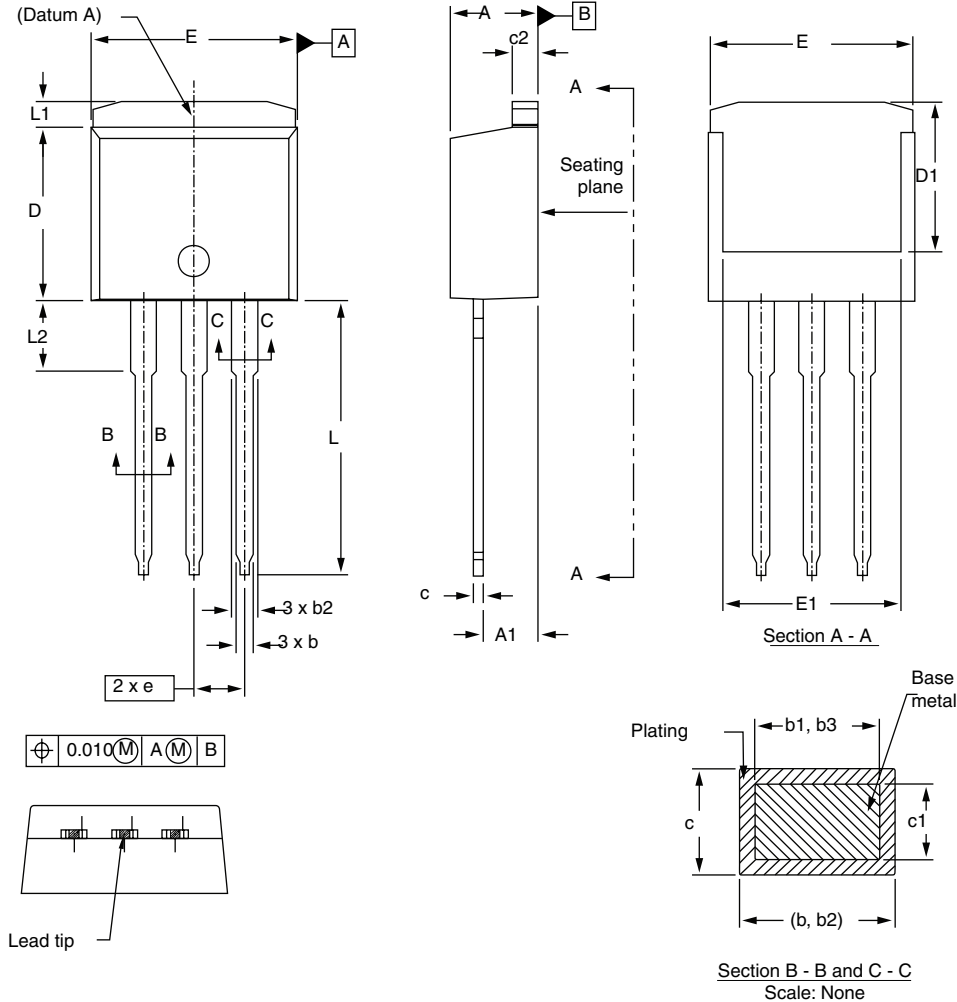
Drain-source breakdown voltage



Drain current vs temperature



I²PAK (TO-262)



DIM.	MILLIMETERS		INCHES	
	MIN.	MAX.	MIN.	MAX.
A	4.06	4.83	0.160	0.190
A1	2.03	3.02	0.080	0.119
b	0.51	0.99	0.020	0.039
b1	0.51	0.89	0.020	0.035
b2	1.14	1.78	0.045	0.070
b3	1.14	1.73	0.045	0.068
c	0.38	0.74	0.015	0.029
c1	0.38	0.58	0.015	0.023
c2	1.14	1.65	0.045	0.065

DIM.	MILLIMETERS		INCHES	
	MIN.	MAX.	MIN.	MAX.
D	8.38	9.65	0.330	0.380
D1	6.86	-	0.270	-
E	9.65	10.67	0.380	0.420
E1	6.22	-	0.245	-
e	2.54 BSC		0.100 BSC	
L	13.46	14.10	0.530	0.555
L1	-	1.65	-	0.065
L2	3.56	3.71	0.140	0.146

Notes

1. Dimensioning and tolerancing per ASME Y14.5M-1994.
 2. Dimension D and E do not include mold flash. Mold flash shall not exceed 0.127 mm per side. These dimensions are measured at the outmost extremes of the plastic body.
 3. Thermal pad contour optional within dimension E, L1, D1, and E1.4.
- . Dimension b1 and c1 apply to base metal only.

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